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Press Release

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Tech-X Corporation at the
[62nd Gaseous Electronics Conference](#)
October 20 - 23, 2009, in Saratoga Springs, NY

Location

Stop by our booth at the 62nd Gaseous Electronics Conference to see a demonstration of new VORPAL 4.0 features. Our technical staff will be available at the booth and will be happy to discuss the details of how VORPAL might fit your modeling needs.

Announcement

We are proud to present the latest release of our electromagnetic plasma simulation software, VORPAL (<http://vorpal.txcorp.com>). VORPAL 4.0 provides for the first time parallel and multi-core capability to the Windows platform (as with previous versions, VORPAL 4.0 also runs in parallel on the Linux and Macintosh platforms). Let VORPAL 4.0 help you take full advantage of your multi-core desktop computer. Other new capabilities include:

- cylindrical coordinates for electromagnetic simulation
- automated eigenfrequency and eigenmode extraction from time-domain simulation
- new secondary electron models that allow simulations of complex metallic and dielectric boundaries of arbitrary shape without stairsteps
- improved post-processing, including automated import into the VisIt software for advanced visualization
- improved documentation, including a detailed, 180-page reference manual, a 160-page users guide, and a 157-page examples guide



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Stop by our booth to see a demonstration of any of these new features of VORPAL 4.0. Our technical staff will be available at the booth and will be happy to discuss the details of how VORPAL might fit your modeling needs.

Also, Tech-X will be sponsoring / presenting a lunch tutorial, Thursday, October 22, on the use of VORPAL for modeling, with examples specific to subject areas for GEC.

Personnel from Tech-X will be presenting posters:

Christine Roark, Paul Mallowney, Kevin Paul, David Smithe, Peter Stoltz, "Benefits of Higher-Order Particles in Simulating an Overdense Plasma Using a Particle-in-Cell Code", Thursday, October 22, 4:00 to 6:00.

Chuangdong Zhou, Peter Stoltz, Seth Veitzer, "Numerical Simulation of Cold Dense Plasma Sputtering with VORPAL", Thursday, October 22, 4:00 to 6:00.

Schedule of Tech-X Events at the 62nd Gaseous Electronics Conference

Thursday, October 22:

Lunch Tutorial sponsored and presented by Tech-X Corporation:

"Use of VORPAL for Modeling, with Examples Specific to Subject Areas for GEC"

4:00 - 6:00 Personnel from Tech-X will be presenting posters:

"Benefits of Higher-Order Particles in Simulating an Overdense Plasma Using a Particle-in-Cell Code," Christine Roark, Paul Mallowney, Kevin Paul, David Smithe, Peter Stoltz.

"Numerical Simulation of Cold Dense Plasma Sputtering with VORPAL," Chuangdong Zhou, Peter Stoltz, Seth Veitzer

See the [62nd Gaseous Electronics Conference](#) for more conference information.